



#### **FEATURES**

- Ultra-High Optical Output
- Four Wire Bonds on Die Corners
- Very Narrow Optical Beam
- Standard 3-Lead TO-39 Hermetic Package Chip Size: 0.026" x 0.026"a

## **Electro-Optical Characteristics at 25°C**

Parameters	Test Conditions	Min	Тур	Max	Units
Total Power Output, P₀	I <sub>F</sub> = 500 mA	55	110		mW
Peak Emission Wavelength, λ <sub>P</sub>	I <sub>F</sub> = 50 mA		850		nm
Spectral Bandwidth at 50%, Δλ	I <sub>F</sub> = 50 mA		40		nm
Half Intensity Beam Angle, θ	I <sub>F</sub> = 50 mA		7		Deg
Forward Voltage, V <sub>F</sub>	I <sub>F</sub> = 500 mA		1.7	2	Volts
Reverse Breakdown Voltage, V <sub>R</sub>	I <sub>R</sub> = 10 μA	5	30		Volts
Rise Time	I <sub>FP</sub> = 50 mA		20		nsec
Fall Time	I <sub>FP</sub> = 50 mA		20		nsec

#### **Absolute Maximum Ratings at 25°C Case**

Parameters	Units		
Power Dissipation <sup>1</sup>	1000 mW		
Continuous Forward Current	500 mA		
Peak Forward Current (10 μs, 200 Hz) <sup>2</sup>	1.5 A		
Reverse Voltage	5 V		
Lead Soldering Temperature (1/16" from case for 10 sec)	260°C		

<sup>&</sup>lt;sup>1</sup> Derate per thermal derating curve above 25°C.

#### **Thermal Parameters**

Parameters	Units		
Storage and Operating Temperature Range	-40°C to 100°C		
Maximum Junction Temperature	100°C		
Thermal Resistance, R <sub>THJA</sub> <sup>1</sup>	150°C/W Typical		
Thermal Resistance, R <sub>THJA</sub> <sup>2</sup>	60°C/W Typical		

<sup>&</sup>lt;sup>1</sup> Heat transfer minimized by measuring in still air with minimum heat conducting through leads.

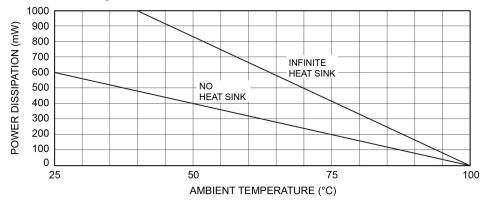
Revision October 10, 2024 Page 1 of 4

<sup>&</sup>lt;sup>2</sup> Derate linearly above 25°C.

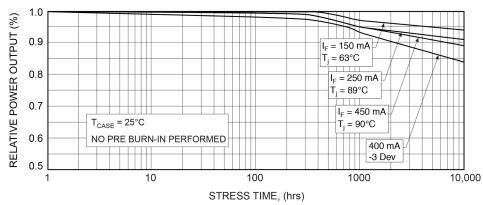
<sup>&</sup>lt;sup>2</sup> Air circulating at a rapid rate to keep case temperature at 25°C.



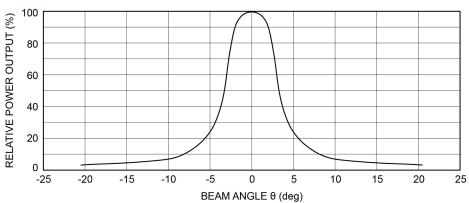
## **Maximum Rated Thermal Derating Curve**



## **Typical Degradation Curve**



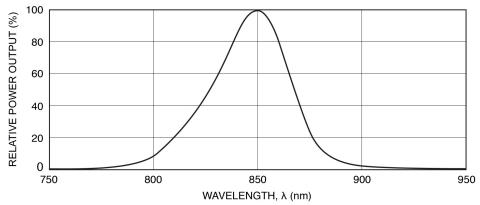
#### **Typical Radiation Pattern**



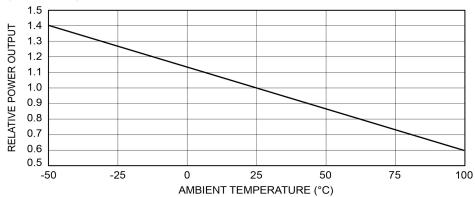
Revision October 10, 2024 Page 2 of 4



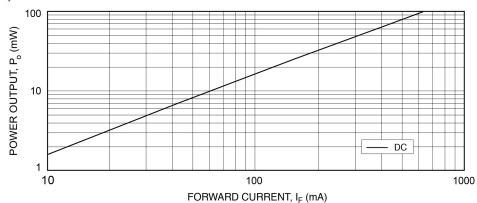
## **Typical Spectral Output**



## **Typical Power Output vs Temperature**



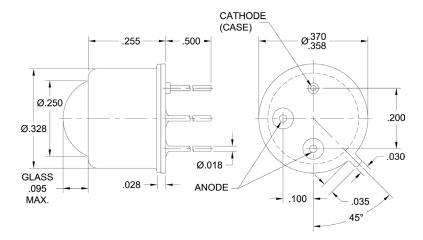
## **Typical Power Output vs Forward Current**



Revision October 10, 2024 Page 3 of 4

# **Super High-Power GaAlAs IR Emitters**

### **Package Information**



All surfaces are gold plated. Dimensions are nominal values in inches unless otherwise specified. Two Anode pins *must be* externally connected together.

Specifications are subject to change without prior notice.